



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

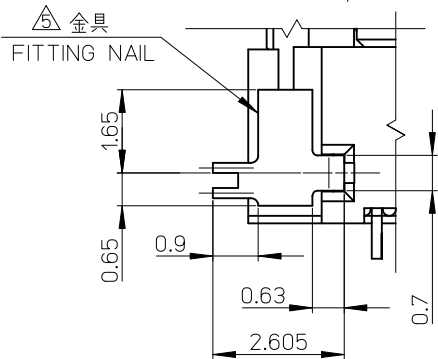
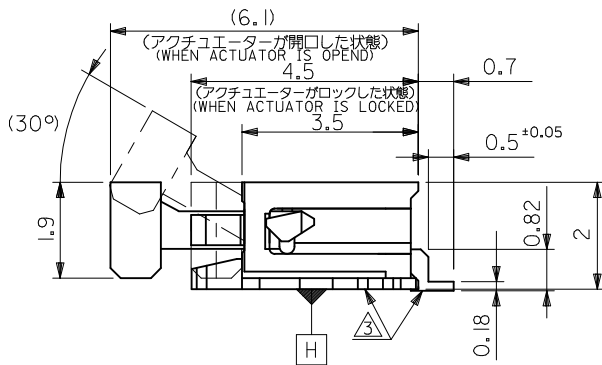
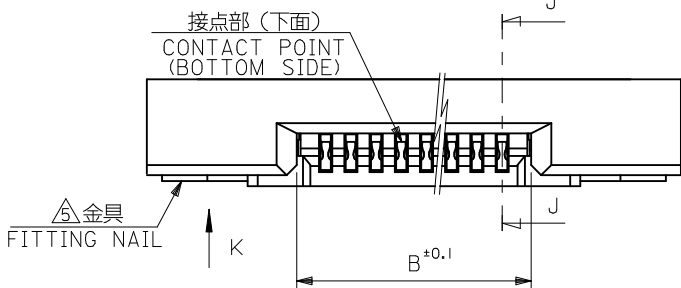
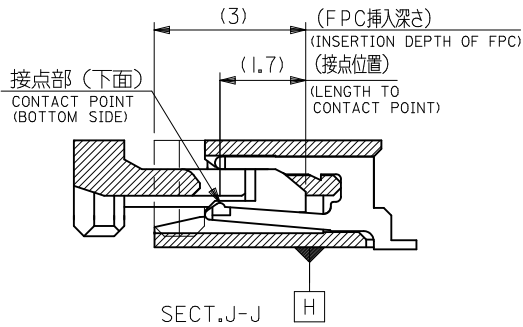
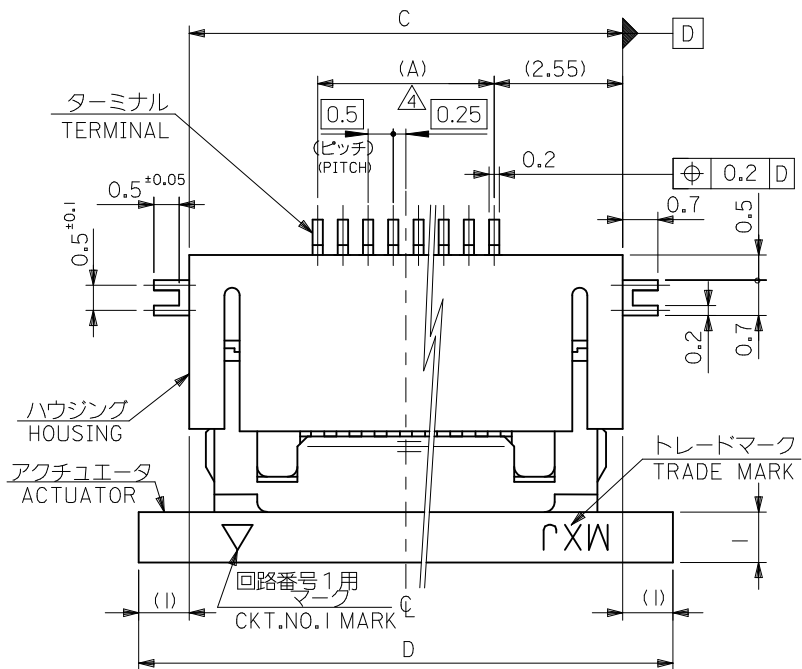
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



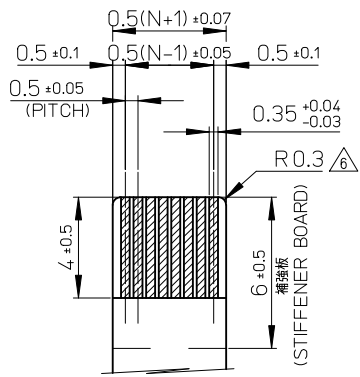
10 9 8 7 6 5 4 3 2 1



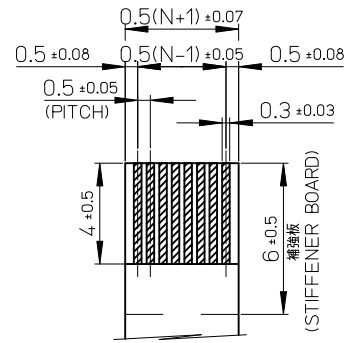
21.6	19.6	15.65	14.5	52437-3071	30
21.1	19.1	15.15	14.0	52437-2971	29
20.6	18.6	14.65	13.5	52437-2871	28
20.1	18.1	14.15	13.0	52437-2771	27
19.6	17.6	13.65	12.5	52437-2671	26
19.1	17.1	13.15	12.0	52437-2571	25
18.6	16.6	12.65	11.5	52437-2471	24
18.1	16.1	12.15	11.0	52437-2371	23
17.6	15.6	11.65	10.5	52437-2271	22
17.1	15.1	11.15	10.0	52437-2171	21
16.6	14.6	10.65	9.5	52437-2071	20
13.6	11.6	7.65	6.5	52437-1471	14
12.6	10.6	6.65	5.5	52437-1271	12
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52437-\*\*-29

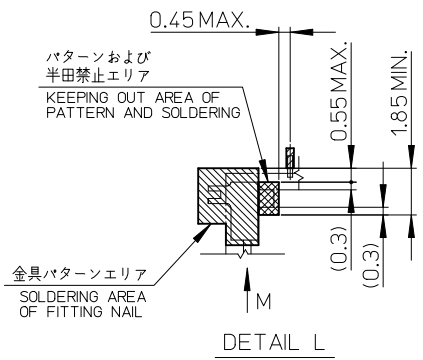
REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:H IJIMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWN BY M.UMEDA DATE 2004/12/08	CHECKED BY K.TOYOTA DATE 2004/12/08	TITLE 0.5 FPC CONN.ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING			
	MATERIAL NO. SEE TABLE		APPROVED BY N.UKITA DATE 2004/12/08		MOLEX INCORPORATED DOCUMENT NO. SD-52437-019		SHEET NO. 1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



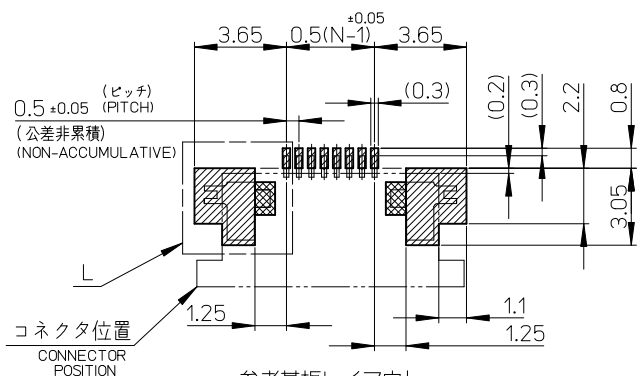
適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.05  
 THICKNESS: 0.3±0.05/-0.05



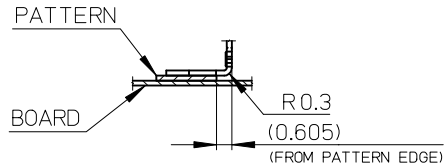
適合金めっきFFC推奨寸法  
 APPLICABLE FFC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.05  
 THICKNESS: 0.3±0.05/-0.05



DETAIL L



参考基板レイアウト  
 (マウント面)  
 RECOMMENDED P.C.BOARD  
 PATTERN DIMENSION (REF.)  
 (MOUNTING SIDE)



VIEW M  
 (DETAIL OF FITTING NAIL  
 ON PATTERN)

注記NOTES

1. 使用材料  
 MATERIAL  
 ハウジング: 46ナイロン、ガラス充填、UL94V-0、白  
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
 アクチュエータ: ポリフェニレンサルフィド (PPS)、ガラス充填、UL94V-0、茶色  
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BROWN  
 ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)  
 TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING  
 金具: リン青銅、ニッケル下地金めっき (t=0.2)  
 FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING
2. エンボステープ梱包時は、アクチュエータがロックした状態になります。  
 IN THE PACKAGE, ACTUATOR OF PART NO.52437-\*\*-29 SHOULD BE LOCKED.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.  
 UPPER DIRECTION: 0.1MAXIMUM  
 LOWER DIRECTION: 0.15 MAXIMUM
- △ 偶数極に適用  
 APPLY FOR EVEN CIRCUIT.
- △ ハターン剥離止め金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
- △ R0.3は、FPCの導体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
7. ソルダータールの平坦度は、0.1MAXIMUMとする。  
 SOLDER TAIL COPLANARITY IS 0.1 MAXIMUM.
8. ELV 及び RoHS 適合品  
 ELV AND RoHS COMPLIANT

FPCについて:

打抜き方向は導体側から補強板側を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。

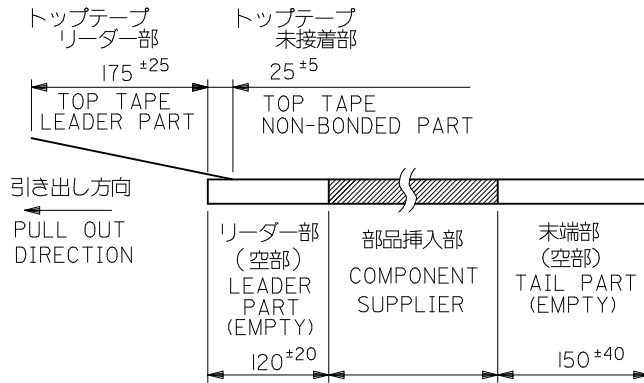
ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION :  
 FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL:  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

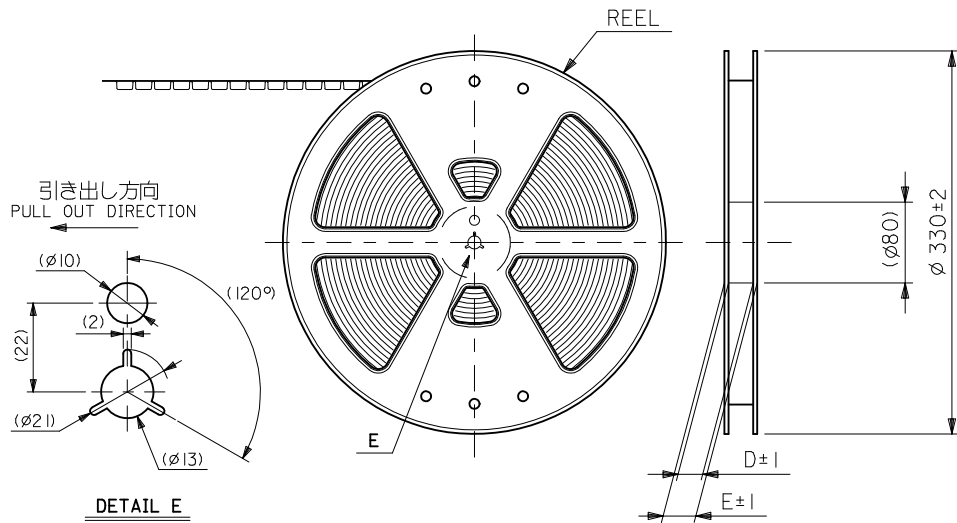
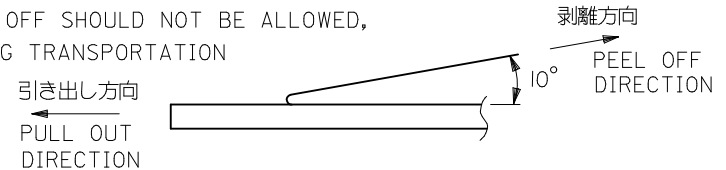
REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:H IJIMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY M.UMEDA	DATE 2004/12/08	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING			
	10 OVER 30 UNDER	± ---	CHECKED BY K.TOYOTA	DATE 2004/12/08	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N.UKITA	DATE 2004/12/08	DOCUMENT NO. SD-52437-019			
REV D	DESCRIPTION ANGULAR ± --- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					SHEET NO. 2 OF 2

注記 NOTES

- 製品番号52437-\*\*29の梱包状態はアクチュエータがロックした状態とする。  
製品の詳細寸法については図面SD-52437-019を参照下さい。  
IN THE PACKAGE, ACTUATOR OF PART NO. 52437-\*\*29 SHOULD BE LOCKED RE DETAILED DIMENSIONS, SEE SD-52437-019.
- 梱包数量：1000個/リール  
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



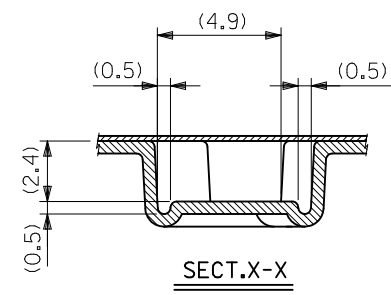
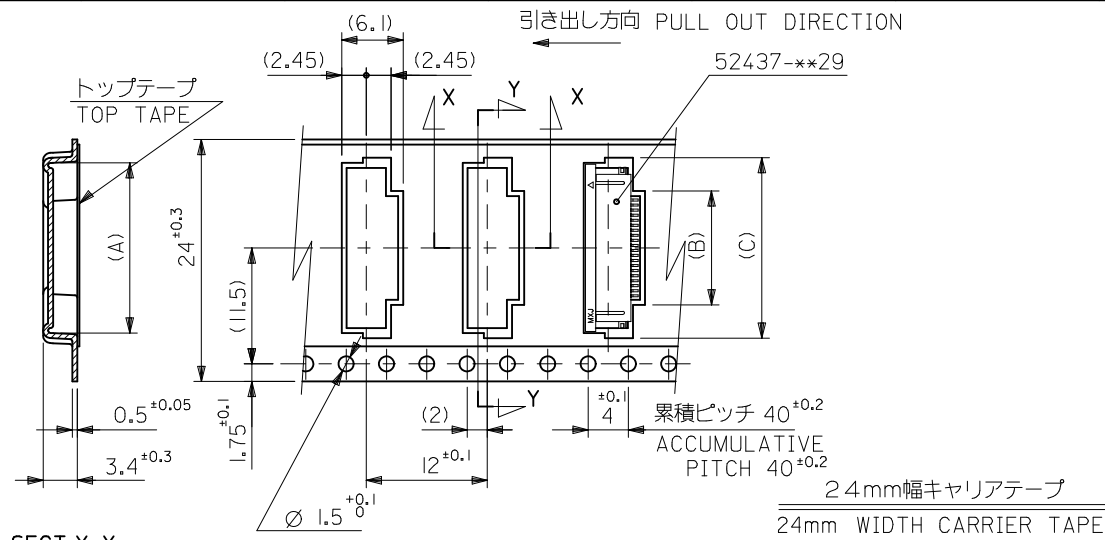
- トップテープの剥離強度：(剥離方向は下図参照)  
0.1N~1.3N {10gf~130gf} 尚、本規格値は、出荷時に適用。  
(但し、輸送時に剥離が発生しない事。)  
PEELING OFF FORCE OF TOP TAPE  
0.1N ~1.3N {10gf ~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION



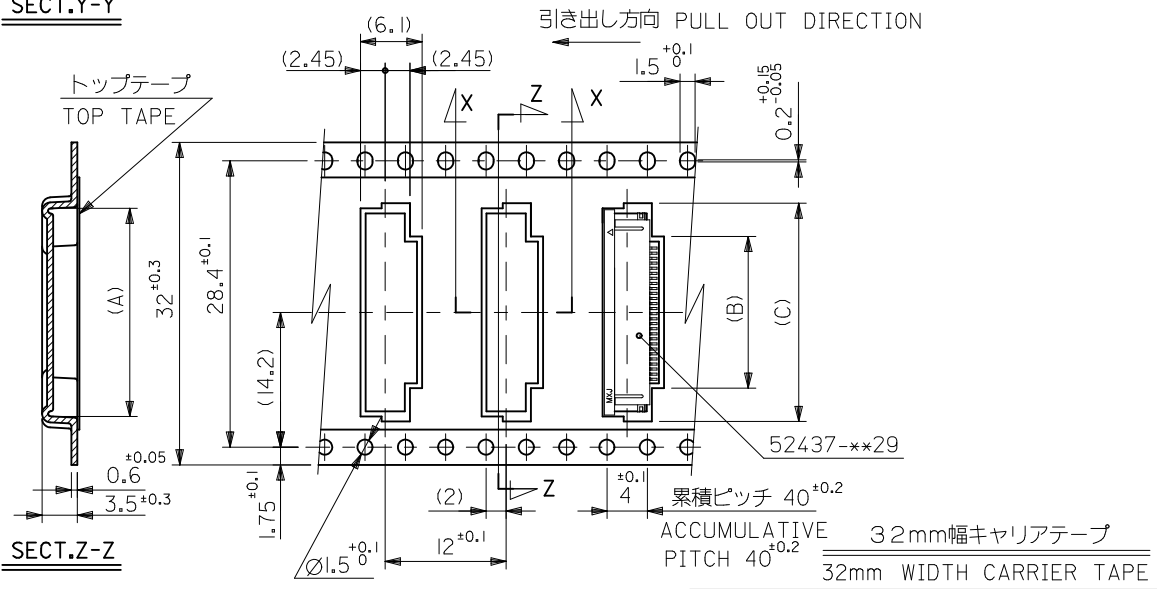
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOPTAPE) : PET, PE, PEF  
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 52437-\*\*91 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52437-\*\*91.

MODEL NO. 52437-\*\*71

REVISED EC NO. J2012-0850 DRWN:KNAGUMO 2011/12/28 CHKD:HIJIMA 2011/12/28 APPR:KMORIKAWA 2011/12/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004-12/08	TITLE 0.5 FPC CONN. ZIF SMT RA WITH TAPE EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004-12/08	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2004-12/08	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-52437-020	SHEET NO. 1 OF 3
REV	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



SECT.Y-Y

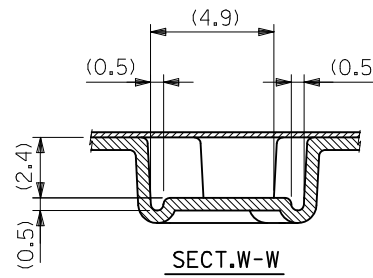
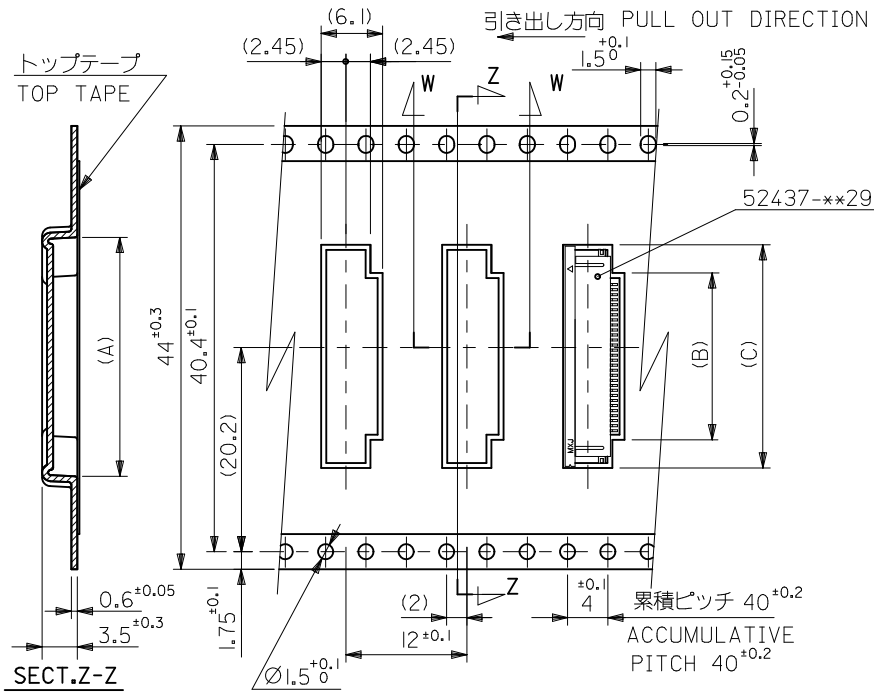


SECT.Z-Z

32	37.4	33.4	22.4	15.8	21.4	52437-2971	29		
			21.9	15.3	20.9	52437-2871	28		
			21.4	14.8	20.4	52437-2771	27		
			20.9	14.3	19.9	52437-2671	26		
			20.4	13.8	19.4	52437-2571	25		
			19.9	13.3	18.9	52437-2471	24		
			19.4	12.8	18.4	52437-2371	23		
			18.9	12.3	17.9	52437-2271	22		
24	29.4	25.4	18.4	11.8	17.4	52437-2171	21		
			17.9	11.3	16.9	52437-2071	20		
			14.9	8.3	13.9	52437-1471	14		
			13.9	7.3	12.9	52437-1271	12		
キャリアテープ幅 CARRIER TAPE WIDTH			E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
						MODEL NO.	52437-**71		

REVISED EC NO.: J2012-0850 DRWN:KNAGUMO 2011/12/28 CHKD:HIJIMA 2011/12/28 APPR:KMORIKAWA 2011/12/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	---	METRIC		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	M.UMEDA	2004/12/08	0.5 FPC CONN. ZIF SMT RA WITH TAPE EMBSTP PKG -LEAD FREE-		
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED		
ANGULAR	±3 °	K.TOYODA	2004/12/08	MATERIAL NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		N.UKITA	2004/12/08	DOCUMENT NO.			SHEET NO.
		SEE CHART		SD-52437-020			2 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							





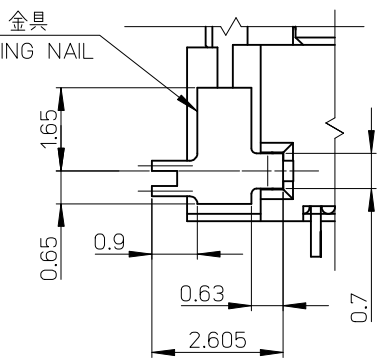
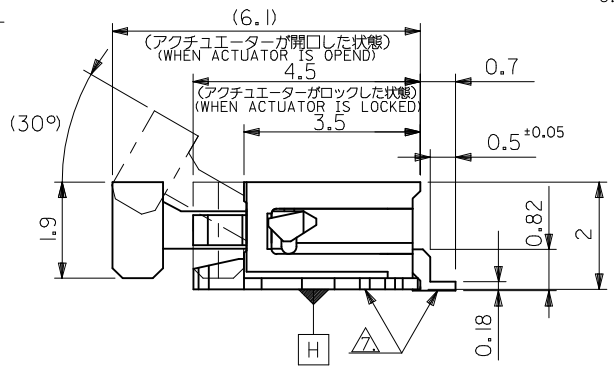
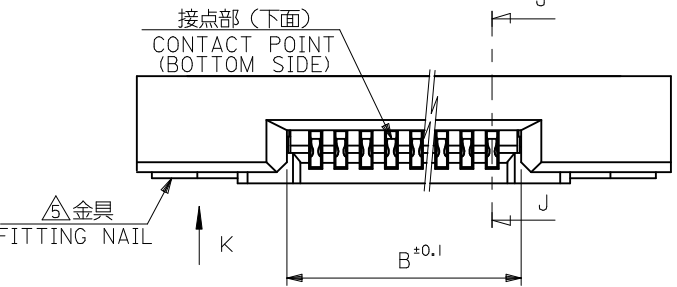
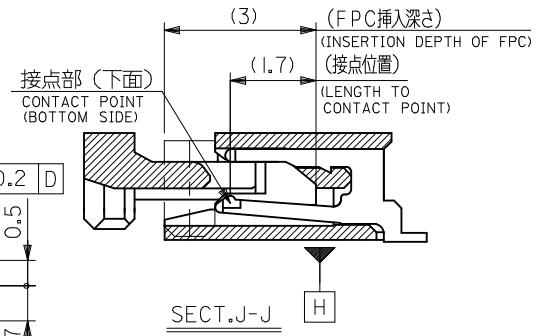
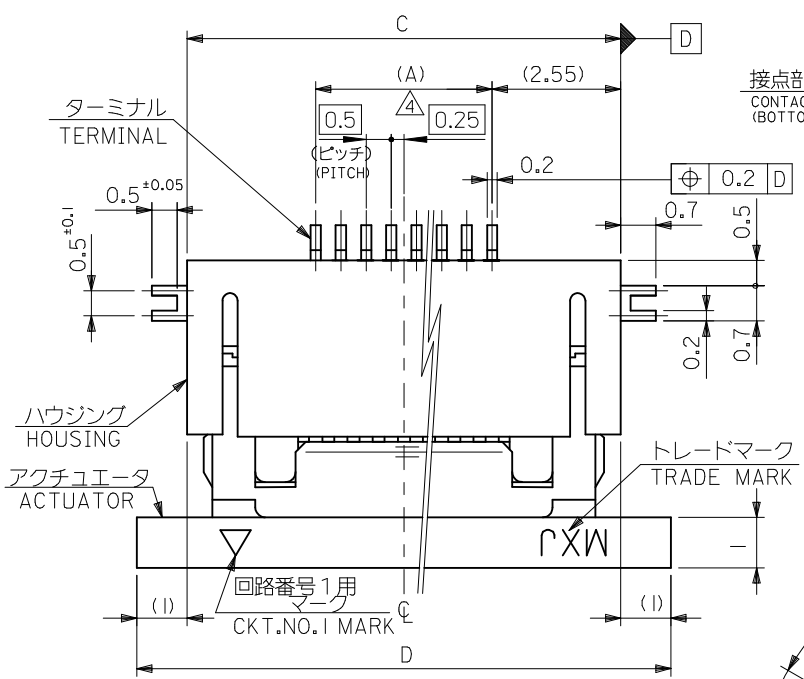
44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

44	49.4	45.4	22.9	16.3	21.9	52437-3071	30
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
						MODEL NO.	25437-**71

REVISED EC NO: J2012-0850 DRWN:KNAGUMO 2011/12/28 CHK'D:HIJIMA 2011/12/28 APPR:KMORIKAWA 2011/12/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/12/08	TITLE 0.5 FPC CONN. ZIF SMT RA WITH TAPE EMBSTP PKG -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004/12/08	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2004/12/08	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-52437-020	SHEET NO. 3 OF 3	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

NOTES

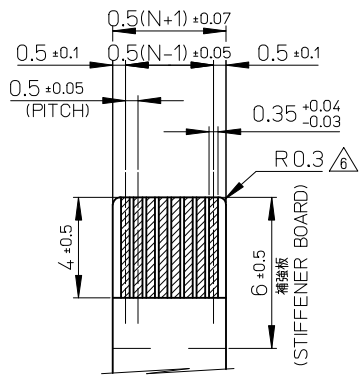
1. 使用材料  
 MATERIAL  
 ハウジング: ポリアミド(PA)、ナチュラル(白色)、ガラス充填、UL94V-0  
 HOUSING: POLYAMIDE NATURAL(WHITE), GLASS FILLED, UL94V-0  
 アクチュエータ: ポリフェニレンサルファイド(PPS)、ナチュラル(茶色)、ガラス充填、UL94V-0  
 ACTUATOR: PPS, NATURAL(BROWN), GLASS FILLED, UL94V-0  
 ターミナル: リン青銅 (t = 0.2)  
 TERMINAL: PHOSPHOR BRONZE (t = 0.2)  
 金具: リン青銅 (t = 0.2)  
 FITTING NAIL: PHOSPHOR BRONZE (t = 0.2)
2. メッキ仕様 PLATING  
 ターミナル TERMINAL  
 鍍銀ビスマスメッキ (1.0 μm以上)  
 TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)  
 下地メッキ: ニッケルメッキ (1.0 μm以上)  
 UNDER PLATING: NICKEL PLATING (1.0 MICROMETER MINIMUM)  
 金具 NAIL  
 鍍メッキ (1.0 μm以上)  
 TIN PLATING (1.0 MICROMETER MINIMUM)  
 下地メッキ: ニッケルメッキ (1.0 μm以上)  
 UNDER PLATING: NICKEL PLATING (1.0 MICROMETER MINIMUM)
3. エンボステープ梱包時は、アクチュエータがロックした状態になります。  
 IN THE PACKAGE, ACTUATOR OF PART NO.52437-\*\*-\*\*22 SHOULD BE LOCKED.  
 偶数極に適用  
 APPLY FOR EVEN CIRCUIT.  
 ハ・ターン制鎖止め金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.  
 R0.3は、FPCの導体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.  
 ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、  
 基準面 H に対して上方向に0.1MAXIMUM、下方向に0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM H.  
 UPPER DIRECTION : 0.1 MAXIMUM  
 LOWER DIRECTION : 0.15 MAXIMUM  
 8. ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT



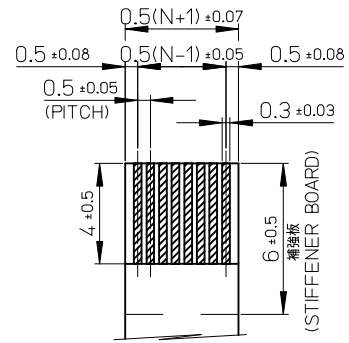
24.1	22.1	18.15	17.0	52437-3533	35
21.6	19.6	15.65	14.5	52437-3033	30
21.1	19.1	15.15	14.0	52437-2933	29
20.6	18.6	14.65	13.5	52437-2833	28
20.1	18.1	14.15	13.0	52437-2733	27
19.6	17.6	13.65	12.5	52437-2633	26
19.1	17.1	13.15	12.0	52437-2533	25
18.6	16.6	12.65	11.5	52437-2433	24
18.1	16.1	12.15	11.0	52437-2333	23
17.6	15.6	11.65	10.5	52437-2233	22
17.1	15.1	11.15	10.0	52437-2133	21
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52437-\*\*-\*\*22

RELEASED EC NO. J2013-1015 DRWN: KMIYAHARA 2012/09/05 CHKD: KTAKAHASHI 2012/09/05 APPR: KMORIKAWA 2013/04/05 REV: O	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION 0.5MM FPC CONN ZIF R/A HOUSING ASSY (LOWER CONTACT) <b>molex</b> SEE CHART SD-52437-023 1 OF 2
		DRAWN BY KMIYAHARA	DATE 2012/09/05	TITLE	
		CHECKED BY KTAKAHASHI	DATE 2012/09/05	DOCUMENT NO. SD-52437-023	
		APPROVED BY KMORIKAWA	DATE 2013/04/05	SHEET NO. 1 OF 2	
MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



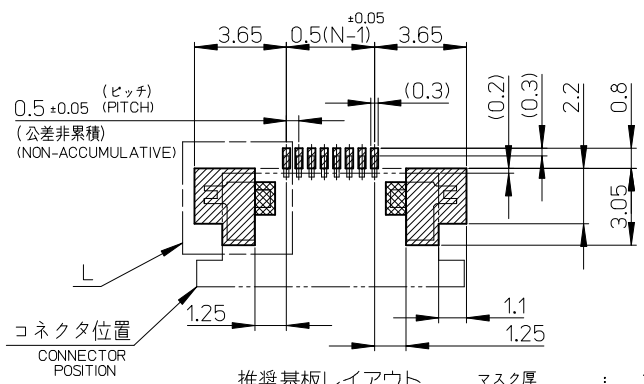
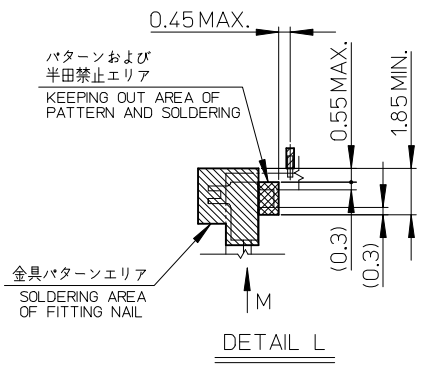
適合FPC推奨寸法  
 APPLICABLE FPC  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.05  
 THICKNESS: 0.3+0.05/-0.05



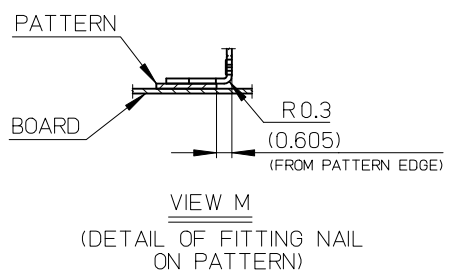
適合FFC推奨寸法  
 APPLICABLE FFC  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.05  
 THICKNESS: 0.3+0.05/-0.05

FPC/FFCについて ABOUT FPC/FFC  
 打ち抜き方向は導体側から補強板側を推奨します。  
 導体部については軟銅箔35μmまたは50μmを推奨します。  
 RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR  
 SIDE TO STIFFENER SIDE  
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL  
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER  
 OR 50 MICROMETER

FPCについてABOUT FPC  
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
 接着剤は熱硬化接着剤を推奨します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE  
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE  
 ON ADHEREND BECAUSE THERE IS A  
 POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE  
 DEFECT IN ELECTRICAL CONTINUITY.



推奨基板レイアウト (マウント面)  
 RECOMMENDED P.C.BOARD  
 PATTERN DIMENSION (MOUNTING SIDE)  
 マスク厚 : 100μm  
 マスク開口率 : 100%  
 SCREEN THICKNESS : 100μm  
 SCREEN OPEN RATIO : 100%



VIEW M  
 (DETAIL OF FITTING NAIL  
 ON PATTERN)

SEE SHEET 1 OF 2 EC NO.: J2013-1015 DRAWN: KMIYAHARA 2012/09/05 CHKD: KTAKAHASHI 2012/09/05 APPR: KMORIKAWA 2013/04/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KMIYAHARA	DATE 2012/09/05	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (LOWER CONTACT)			
	10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2012/09/05				
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2013/04/05				
ANGULAR	± --- °	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-52437-023		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

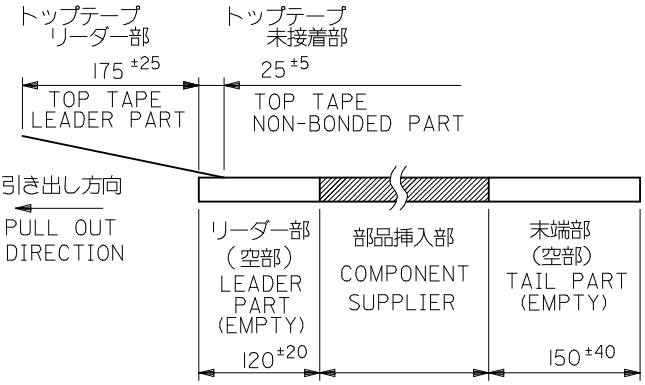


注記 NOTES

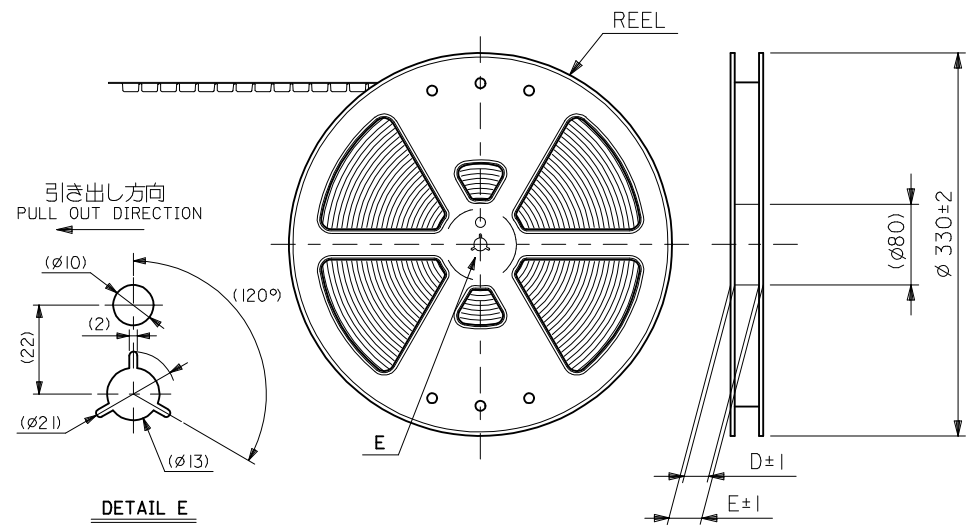
1. 製品番号52437-\*\*22の梱包状態はアクチュエータがロックした状態とする。  
 製品の詳細寸法については図面SD-52437-023を参照下さい。  
 IN THE PACKAGE, ACTUATOR OF PART NO. 52437-\*\*22 SHOULD BE LOCKED  
 RE DETAILED DIMENSIONS, SEE SD-52437-023.

2. 梱包数量：1000個/リール  
 NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. カバーテープの剥離強度については、IEC60286-3に準拠  
 COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
5. 材料 (MATERIAL)  
 キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)  
 トップテープ (TOPTAPE) : PET, PE, PEF  
 リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>  
 POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
6. ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT



DETAIL E

RELEASED EC NO: J2013-1015 DRWN: AISHII 2012/09/10 CHKD: TAKAHASHI 2012/09/10 APPR: KMORIKAWA 2013/04/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AISHII	DATE 2012/09/10	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY  <b>molex</b> DOCUMENT NO. SD-52437-024 SHEET NO. 1 OF 3		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/10			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/04/05			
ANGULAR	±3 °	MATERIAL NO. SEE CHART					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				